

Open Domain Specific Architecture(ODSA)

CREATING OPEN CHIPLET ECOSYSTEM UNDER OPEN COMPUTE PROJECT

June 19th HiPChips ISCA Workshop 2022

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Open Ecosystem Lead, Meta
Co-Chair OCP Incubation Committee

Bapi Vinnakota ODSA Project Lead, Broadcom





Agenda

Overview: Community, charter

Progress towards a fully open, practical D2D stack

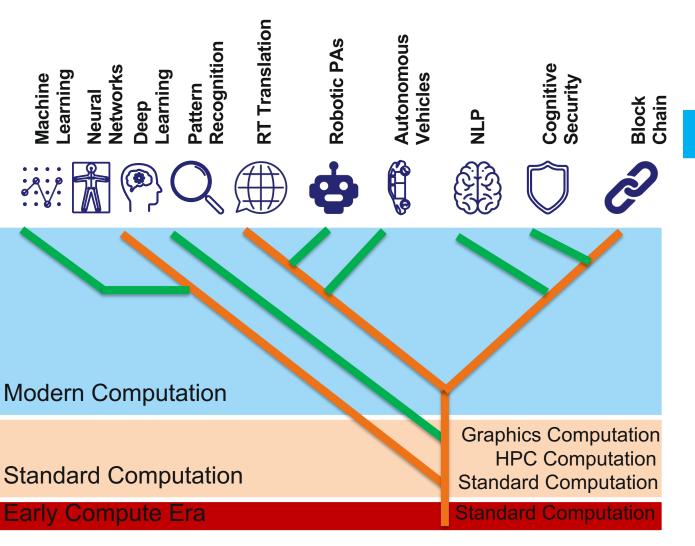
How to participate

Everything presented is the result of active and significant community collaboration



DSA: Accelerators and Chiplets

Domain-specific architectures (DSAs) to accelerate targeted compute-intensive workloads.



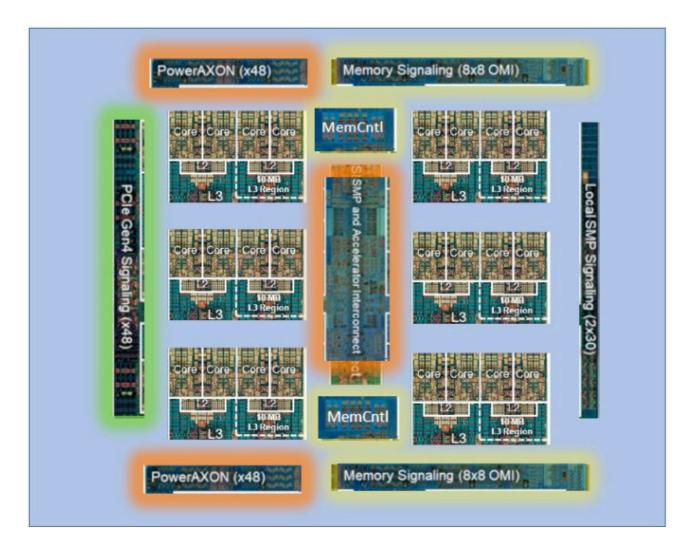
AI/ML/data workload explosion needs DSAs

Dharmesh Jani, Meta: ODSA Workshop, Regional Summit, Amsterdam, Sep. 2019



DSAs built using chiplets with open standard D2D interfaces

Chiplet: Die designed to be used with other die in a package, usually with proprietary interfaces.

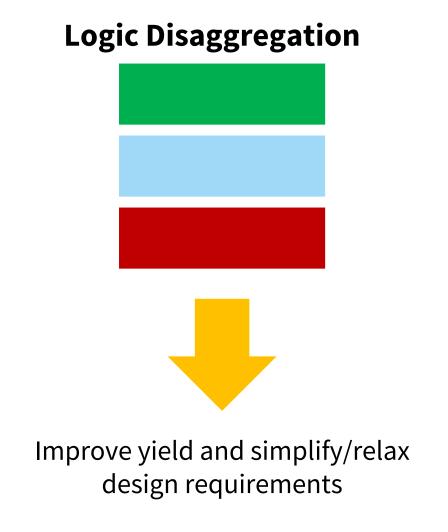


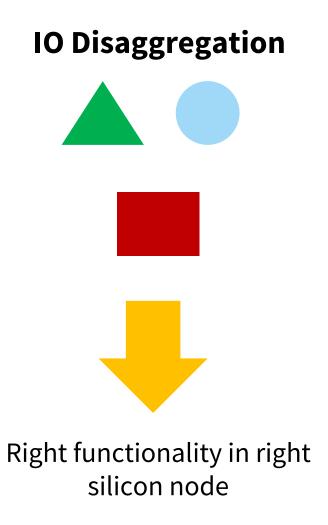
IBM Power 9: potential modularity

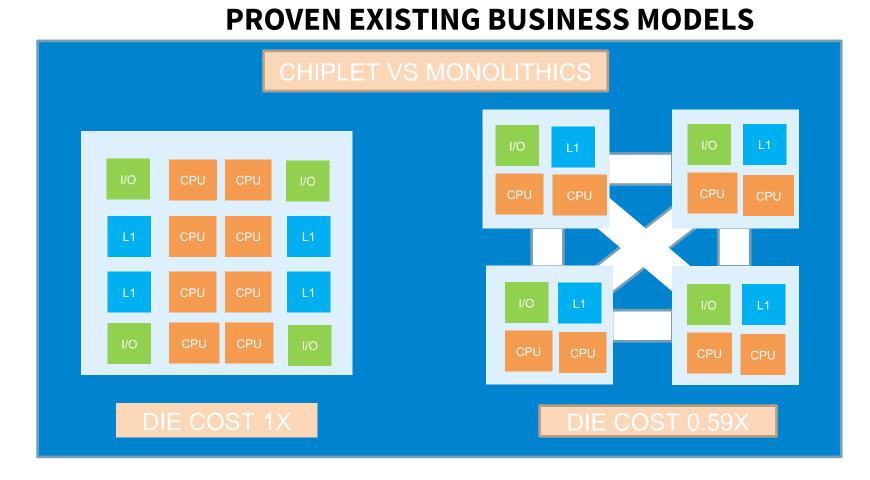
Jeff Stuechli, Josh Friedrich, IB: ODSA Workshop, IBM, San Jose, Sep. 2019

Chiplet Based Domain-Specific Architectures

2018 Turing lecture by John Hennessy and David Patterson talked about coming age of DSAs

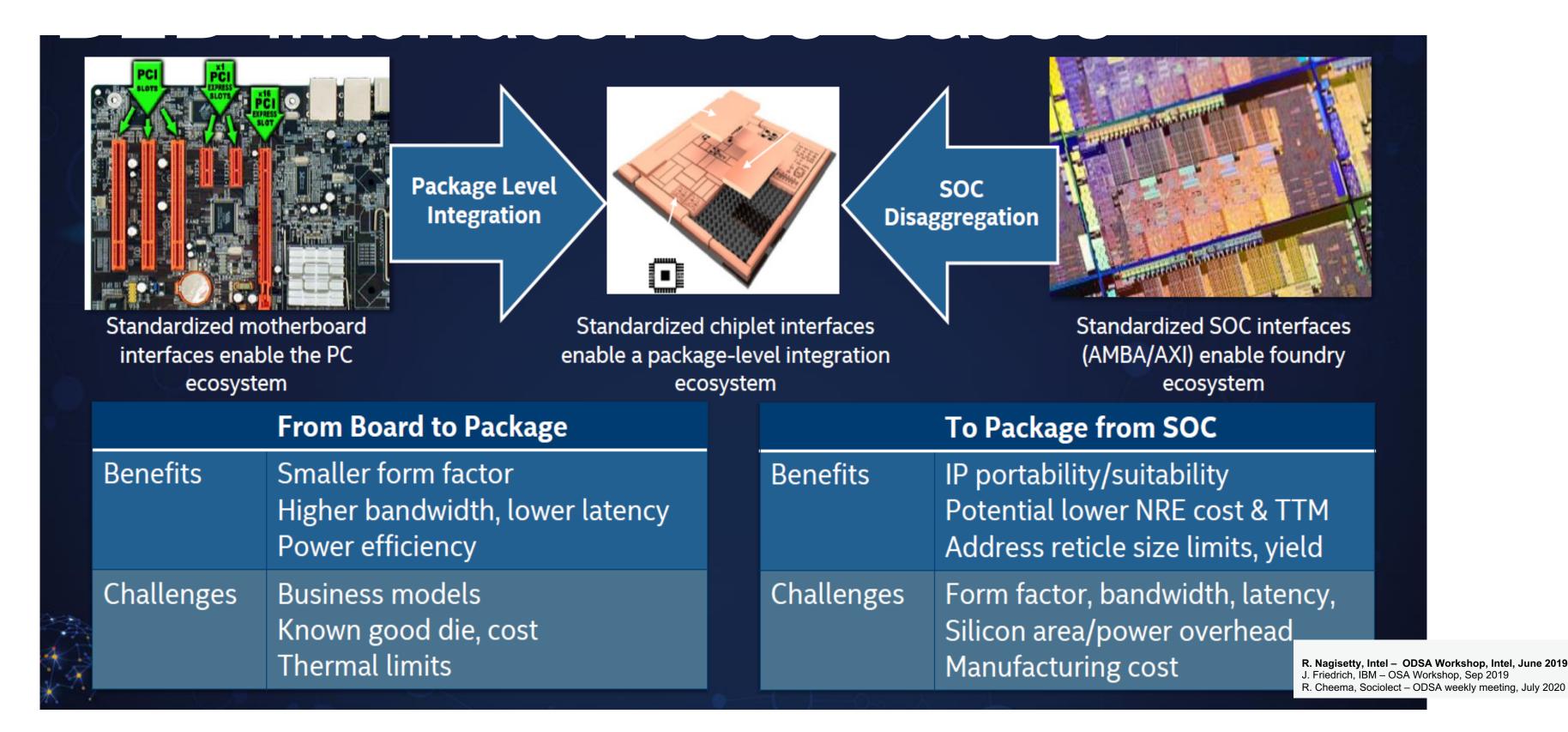




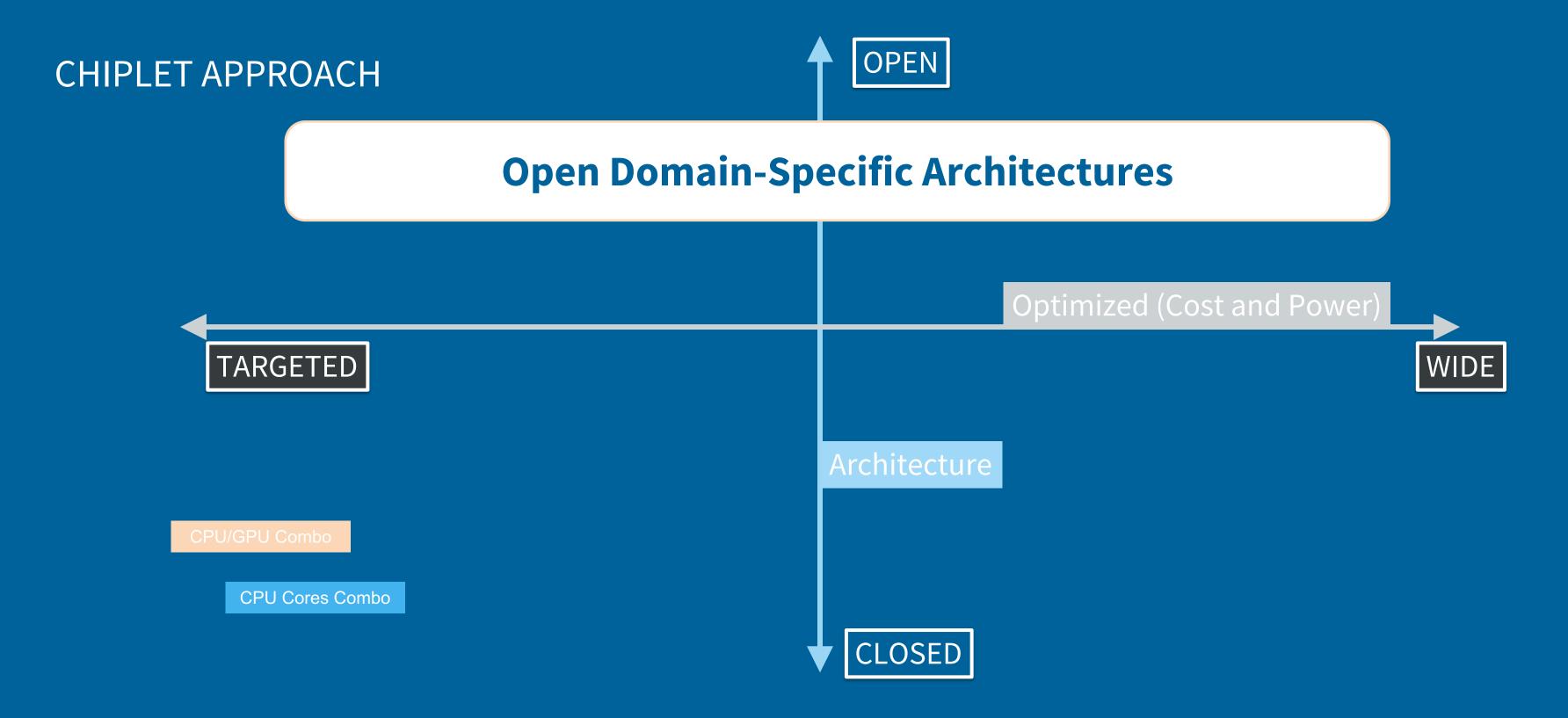


[L. Su, IEDM'17]

D2D Interface: Use Case



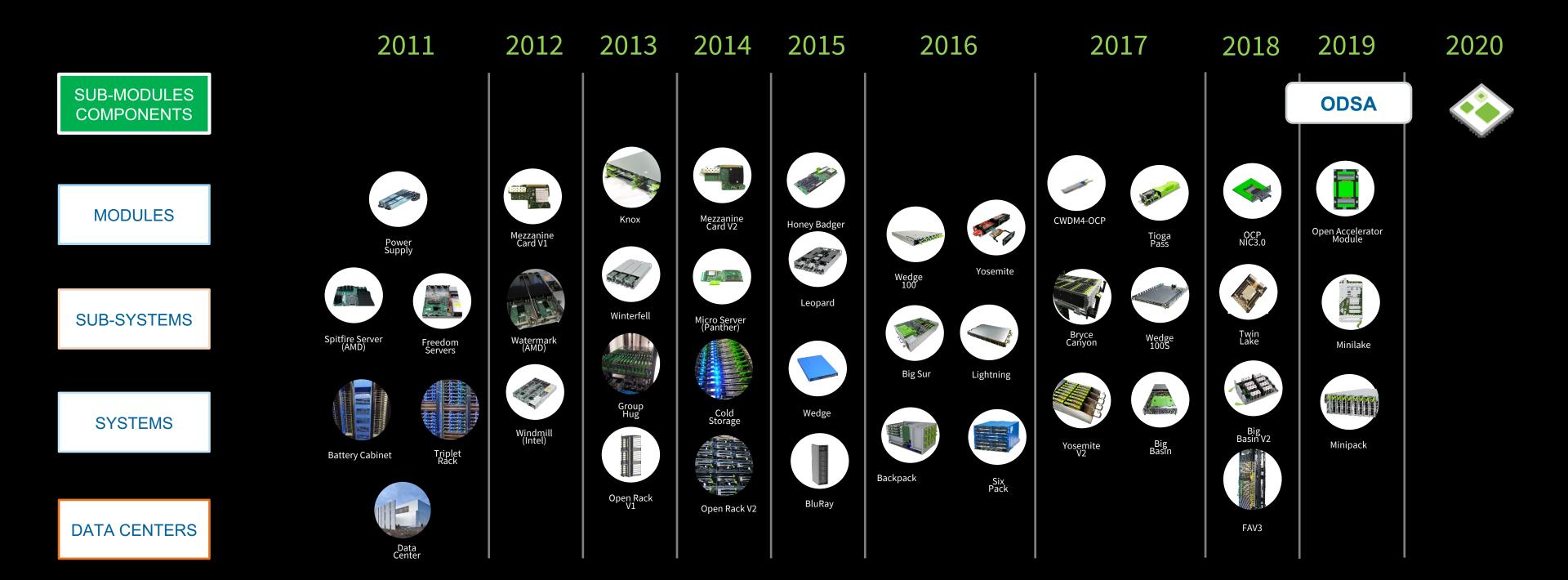
Open Domain-Specific Architecture (ODSA)



OCP Evolution

2011 2012 2013 2014 2015 2016 2017 2018 2019 2020 . **MODULES** Mezzanine Card V2 CWDM4-OCP Honey Badger Open Accelerator Module Mezzanine Card V1 OCP NIC3.0 Tioga Pass 337 Yosemite Leopard Winterfell **SUB-SYSTEMS** Micro Server (Panther) Minilake Lightning Wedge **SYSTEMS** Minipack **Battery Cabinet** Open Rack V1 Open Rack V2 **DATA CENTERS** FAV3

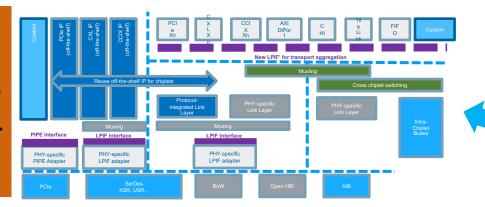
ODSA is the next step...



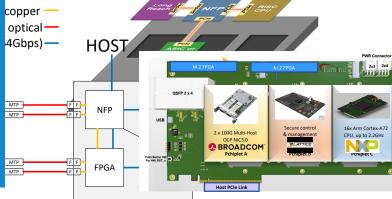
ODSA Charter

ODSA Activities

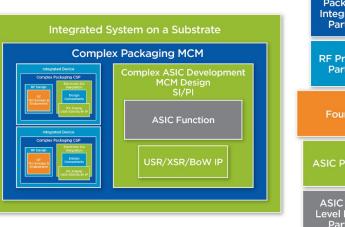
Open D2D
Interface
Reduce barrier
to interoperation



Reference Designs Starting point for new designs



Reference
Workflows
Reusable, open
practices



Package/ Integration Partner

RF Product Partner

Foundry

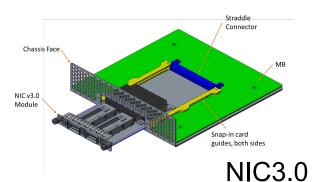
ASIC Provider

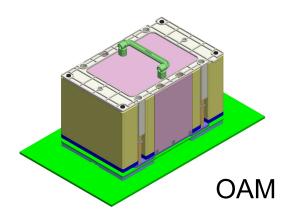


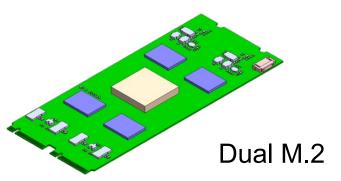
Chiplet Marketplace

Integrate best-in-class chiplets from multiple vendors through open interfaces

OCP modular form factors







ODSA Charter

ODSA Activities

Open D2D
Interface
Reduce barrier

Specifications
BOW
OpenHBI
DiPort etc..

Reference

Designs
Starting point for new designs

to interoperation

Reference Designs
MARA Board
BOW Interop Vehicle

Reference
Workflows
Reusable, open
practices

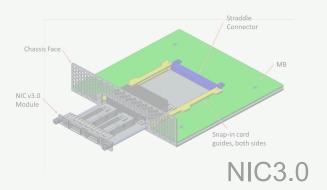
Reference
Workflows
Power Models
Cost Models
White Papers

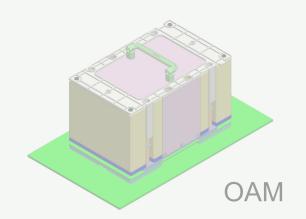


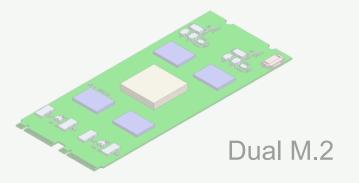
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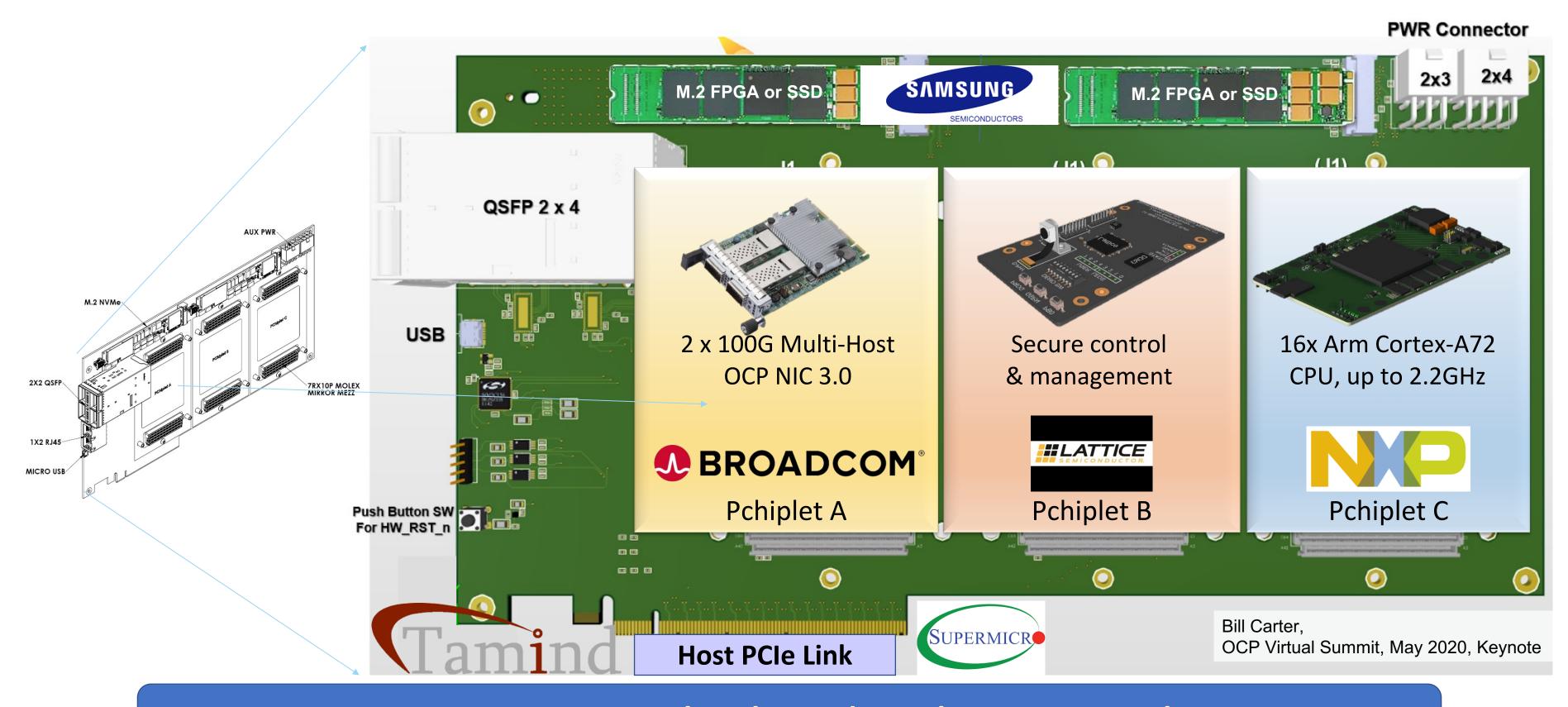
OCP modular form factors





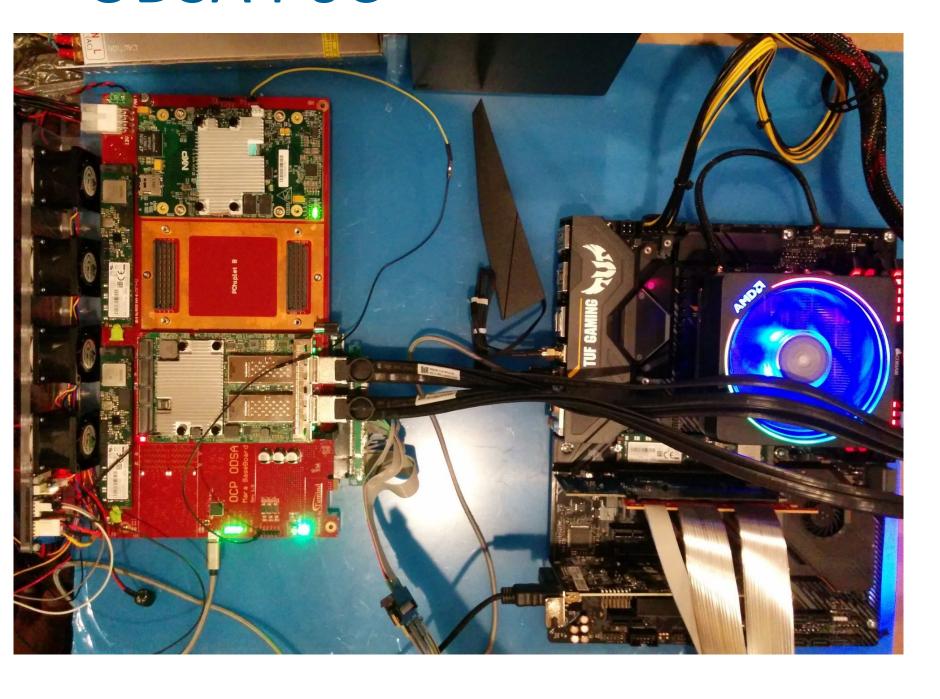


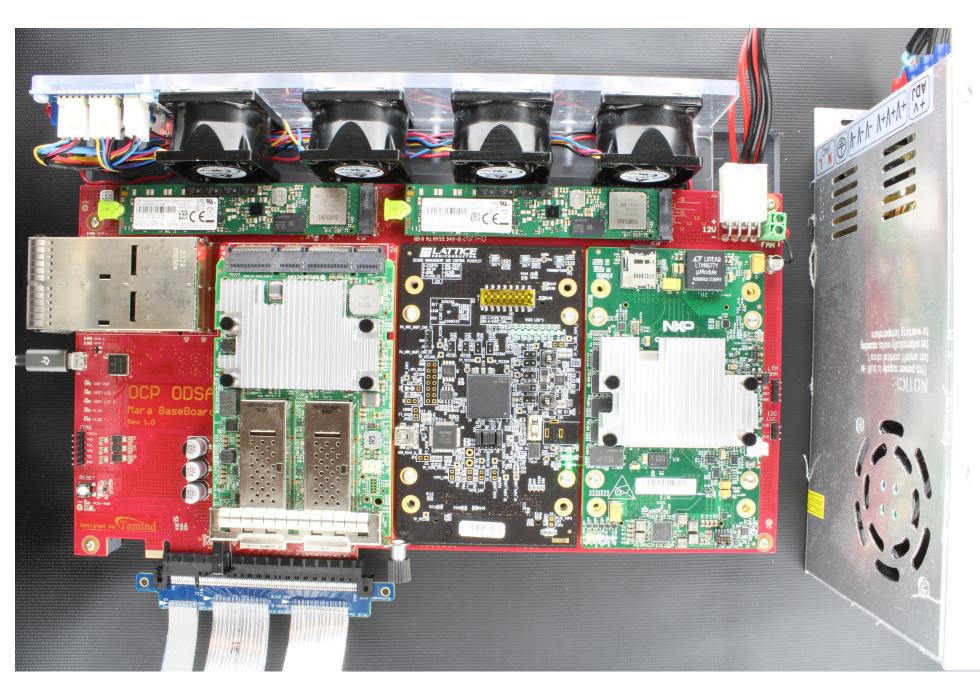
ODSA Accelerator PoC Kit



Design your own Pchiplet, develop an application

ODSA PoC



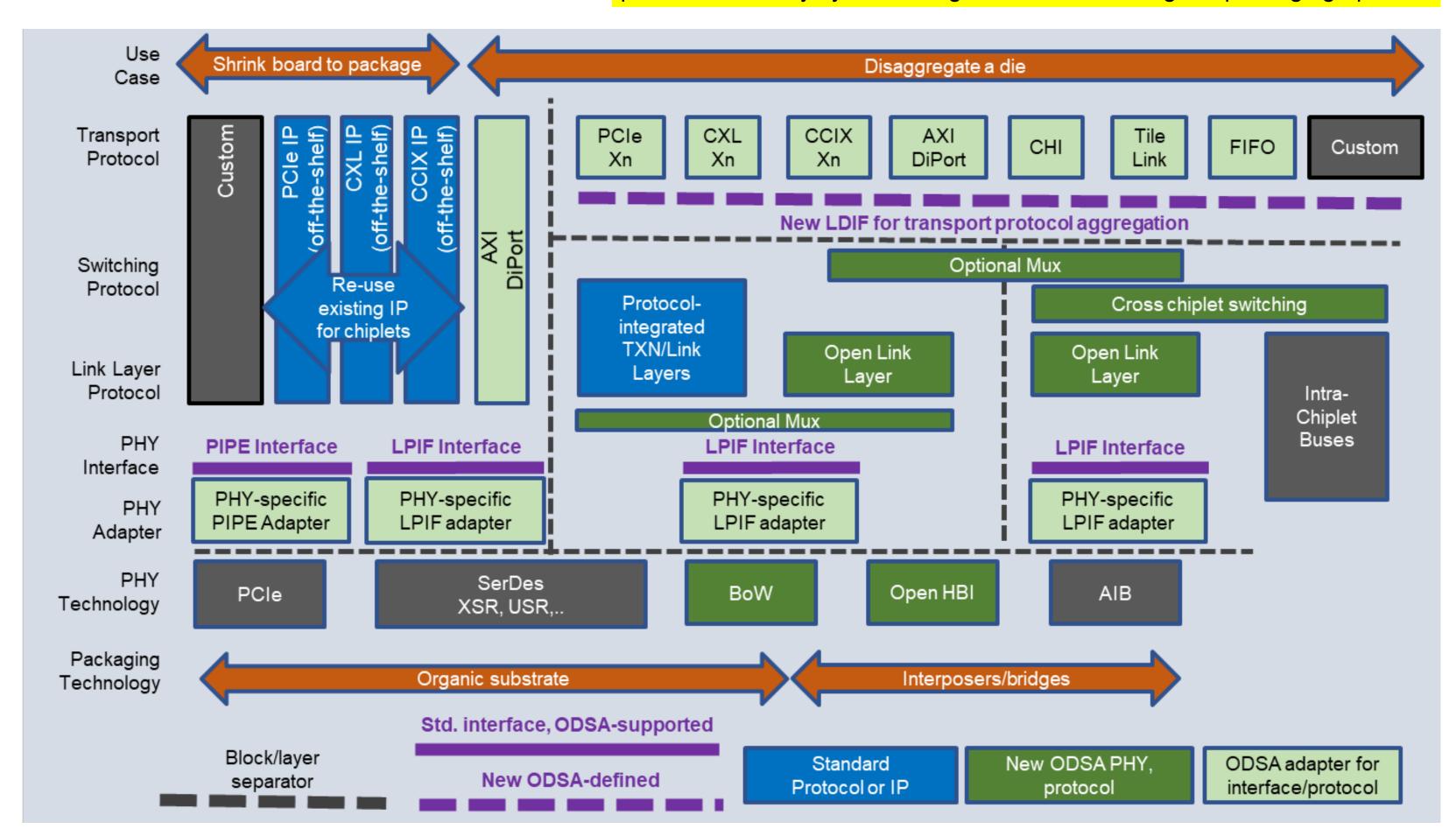


Storage Acceleration Workshop in August 2021



ODSA Stack:

A stack for a marketplace to support the most popular data transaction protocols used by system designers on a wide range of packaging options



Attendees and Participants:

IP providers, EDA

Service providers

Attendance and/or participation do not imply corporate endorsement



Test,

Integration

Systems vendors, End users, ISVs, Service Providers





ODSA Community

Workstream	Leader	Value	Output
ODSA	Bapi Vinnakota	First vertical protocol+PHY D2D stack	Specifications, 15+ refereed technical papers
Bunch of Wires	Elad Alon	First cross-technology scalable clock-forwarded PHY	BoW Draft Spec
Business	Ravi Agarwal	Largest ever OCP workshop Chiplet cost model	Chiplet cost model
CDX	David Ratchkov	First cross-industry open workflow models	Design flow white paper
Cross-PHY	Shahab Ardalan	Industry-standard objective metrics to compare D2D PHYs	Cross-PHY spreadsheet
End User	Dharmesh Jani	Structured flow of requirements	HipChips Conference
Link Layer	Open	Lightweight cross-protocol cross-PHY	DiPort controller
OpenHBI	Kenneth Ma	Leverage most popular chiplet technology	OpenHBI specification
Prototyping	JP Balachandran	Fully collaborative open, community-funded effort	BoW Test Chip ODSA Board Prototype

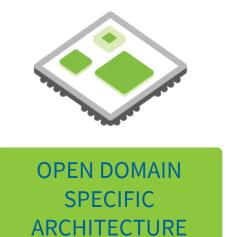


2022 Plans

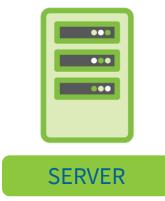
- Support industry efforts to advance an open chiplet ecosystem
 - Collaborate with UCIe
 - e.g., align the second generation of our work OpenHBI, BoW, DiPort, Link Layer...
 - Some ODSA work is entirely complementary CDX, Chiplet business model, KGD model
 - Continue to collaborate with the IEEE, Chips Alliance,....
- Continue the great work we have been doing!
 - ODSA solutions are the first open industry effort for die disaggregation
 - Ecosystem is geared for all use cases; compute, accelerators,
- •Multiple chips/test-chips are in flight, and an ecosystem is already forming today's session



Join ODSA to drive innovation!



- Join a work stream, each meets weekly
- Help with the PoC, software, use case dev
- Review, help complete documents in flight
- Need packaging and test definition and work streams
- Make chiplets with, IP for, the open ODSA stack



- https://www.opencompute.org/wiki/Server/ODSA
- Join us at the OCP Fall Summit in Oct 2022

THE END!

